

## 2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (VIH) and input low (VIL) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICKit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 3 and MPLAB REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

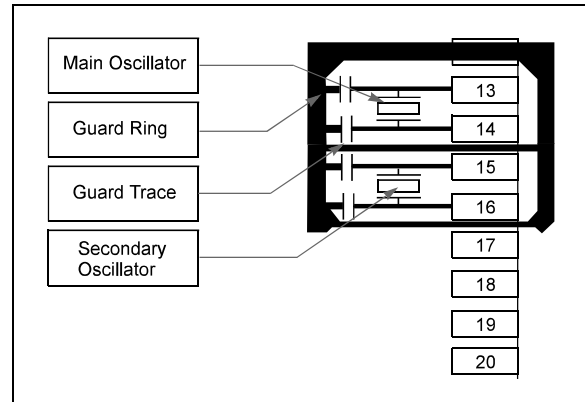
- "Using MPLAB® ICD 3" (poster) DS51765
- "MPLAB® ICD 3 Design Advisory" DS51764
- "MPLAB® REAL ICE™ In-Circuit Emulator User's Guide" DS51616
- "Using MPLAB® REAL ICE™ In-Circuit Emulator" (poster) DS51749

## 2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For details, see [Section 9.0 "Oscillator Configuration"](#) for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

**FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT**



## 2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to  $3 \text{ MHz} < F_{IN} < 5.5 \text{ MHz}$  to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLDBF to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration Word.

## 2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic-low state.

Alternatively, connect a 1k to 10k resistor between Vss and unused pins and drive the output to logic low.